COINS 2019

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Scope of Special Session: Advanced Stacking Many-core Systems and Architectures

With an advancement in both computing architectures and process technology, many-core architectures are going to have hundreds of cores into a single chip. By increasing number of cores, it is possible to improve the performance while keeping the power consumption at the bay. This trend has reached the deployment stage in parallel and network-based systems benefiting some emerging applications such as machine learning, GPU, MPSoC, etc. Network on Chip (NoC) has been proposed as the most viable solution to meet the performance and design productivity requirements of the complex on-chip communication infrastructure. On the other hand, in the recent years, the emerging Through Silicon Via (TSV)-based die stacking three-dimensional (3D) IC process provides a novel connecting approach, which can reduce the wire delay between dies. Although the 3D IC technology and NoC interconnection can reduce the many-core design complexity, the trend to merge multiple functions into one device makes the design and integration of these many-core system even more problematic, such as large power density, low energy efficiency, serious thermal problem, etc. This special session addresses all aspects of emerging NoC and 3D IC architectures for the energy-efficient computing in parallel and distributed multi-core and many-core systems.

Proceeding & Submission Guidelines

COINS is sponsored by **IEEE Council on Electronic Design Automation (CEDA).**, The proceeding will be published in **ACM**. Accepted papers are allowed six pages in the conference proceedings free of charge. Each additional page beyond six pages is subject to the page charge at 150 Euro per page up to the eight-page limit.

Extended versions of selected best papers will be published in a special issue of the ISI indexed Elsevier journal "Microprocessors and Microsystems: Embedded Hardware Design" (**MICPRO**) having the 2016 Impact Factor as high as 1.025

In order to conduct a blind review, no indication of the authors' names should appear in the manuscript, references included.

Important Dates

Submission Deadline: January 10, 2019

Notification Date: January 15, 2019

Camera-ready: January 31, 2019

Conference Dates: May 5-7, 2019

Grant

COINS Executive Committee is pleased to announce registration grants for highly skilled students who have an accepted paper. We are especially looking forward to applications from Middle East, and Asia.

All questions about submissions should be emailed to Dr.-Ing. Farshad Firouzi (farshadfirouzi@gmail.com).